

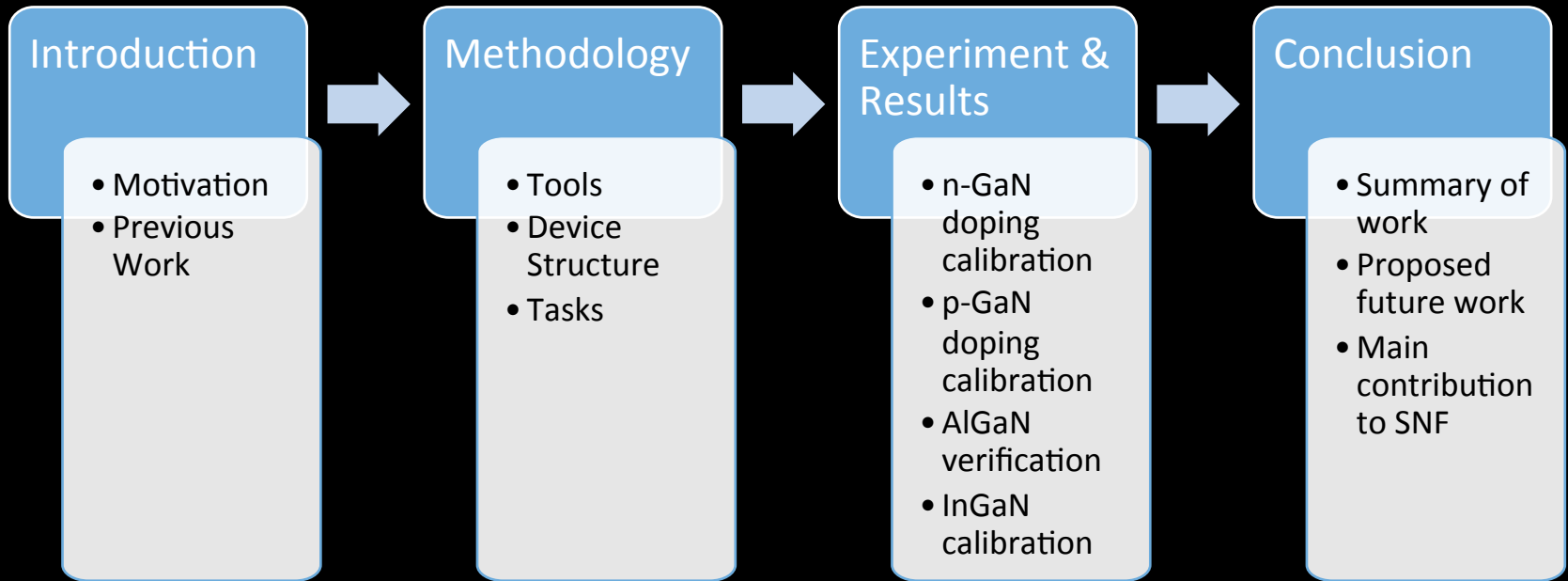
MOCVD Growth Calibration for GaN LED on Silicon

Jieyang Jia, Yusi Chen

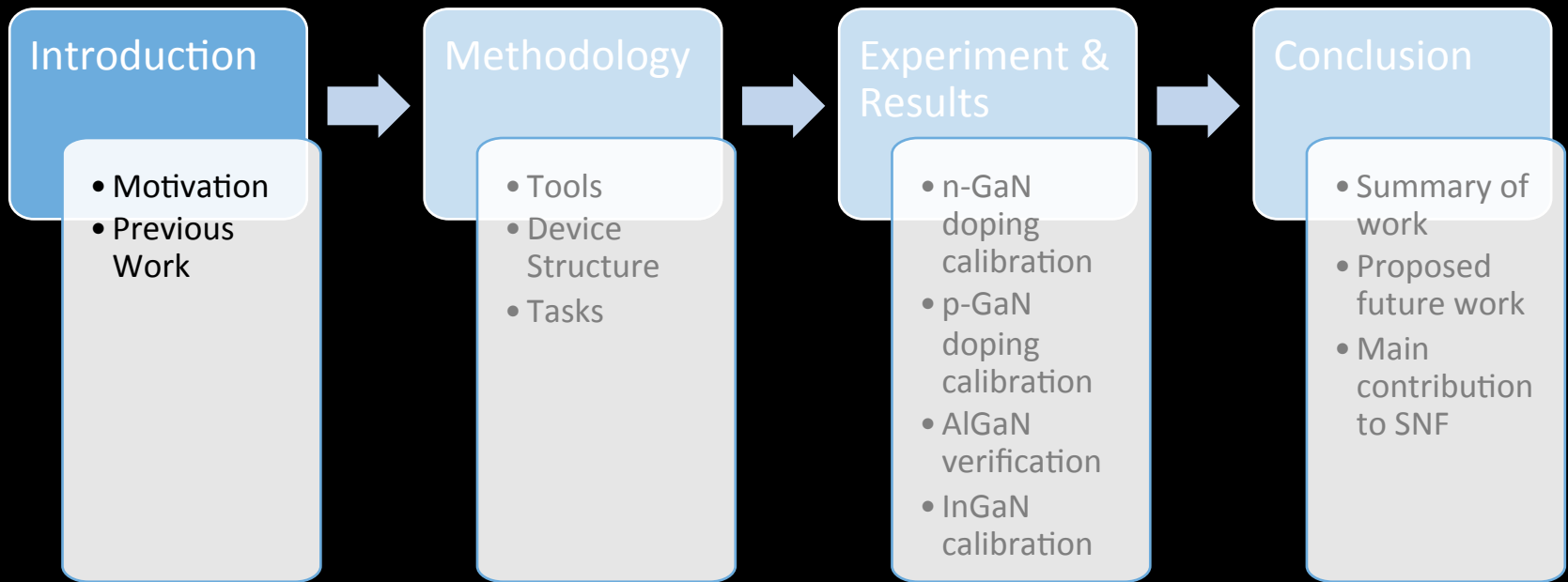
Mentored by Xiaoqing Xu

EE412, Spring 2015

Outline



Outline

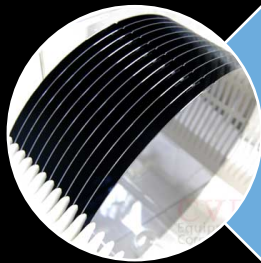


Motivation



UV/blue/white light LED

- Multi-billion \$ market
- Nobel prize



Silicon substrate

- Cost effective
- But makes growth challenging

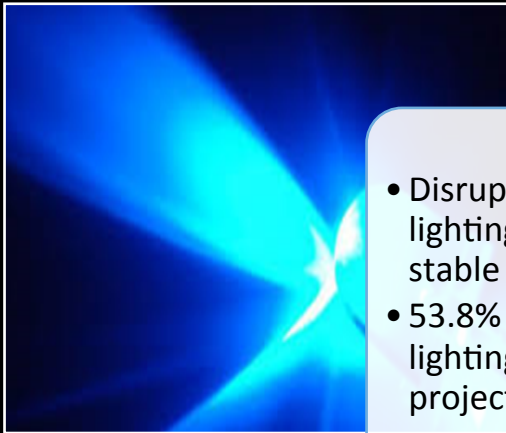


Value to SNF

- Enabling short-wavelength LED research
- Making new III-N materials available in SNF

Previous Work

UV/blue/white light LED



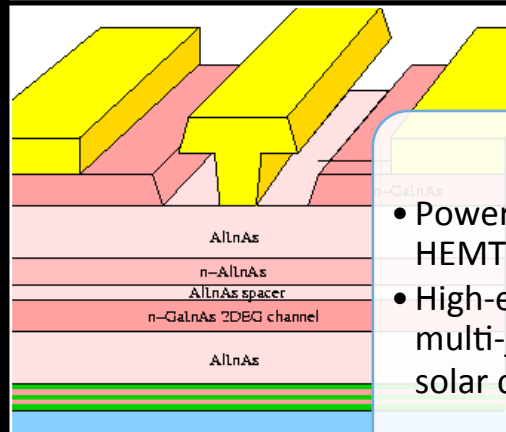
- Disrupting the lighting 100-year-stable industry
- 53.8% street lighting, 93.8% projected by 2023²

III-N MOCVD Technology



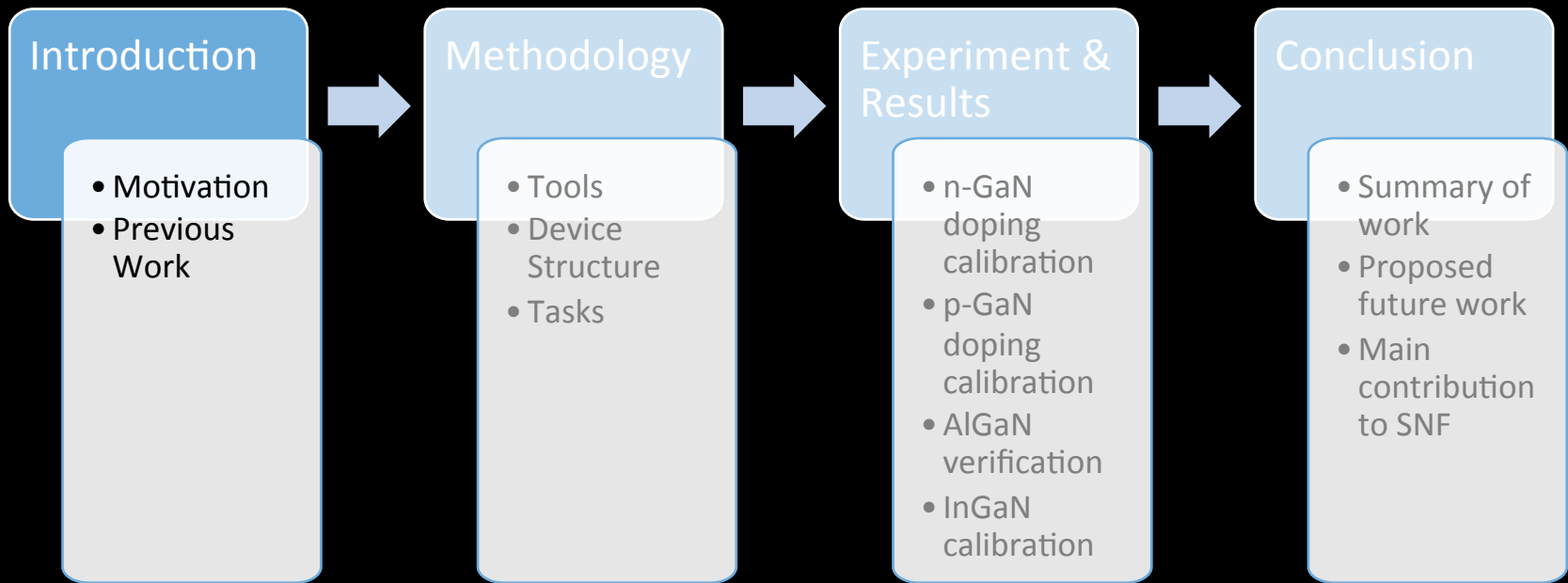
2014 Nobel prize in Physics

Other Applications



- Power devices & HEMTs
- High-efficiency multi-junction solar cells

Outline



Tools

- Aix-ccs MOCVD
- Hall Measurement
- Innotec & RTA
- SEM & IV
- XRD



Test Epi Structure

200 nm n-GaN (Si or Mg)	To calibration doping
15 nm n-Al _{0.2} Ga _{0.8} N (Si)	To calibration composition
1.5 μm GaN	
560 nm Al _{0.2} Ga _{0.8} N	
345 nm Al _{0.5} Ga _{0.5} N	Buffer layers
140 nm Al _{0.8} Ga _{0.2} N	
210 nm AlN	
(111) Si	Substrate (standard clean)

List of Tasks

n-GaN

- Investigate relation between doping density and SiH_4 flow rate

p-GaN

- Investigate relation between doping density and
 - Mg flow rate
 - Growth temperature
 - Annealing temperature

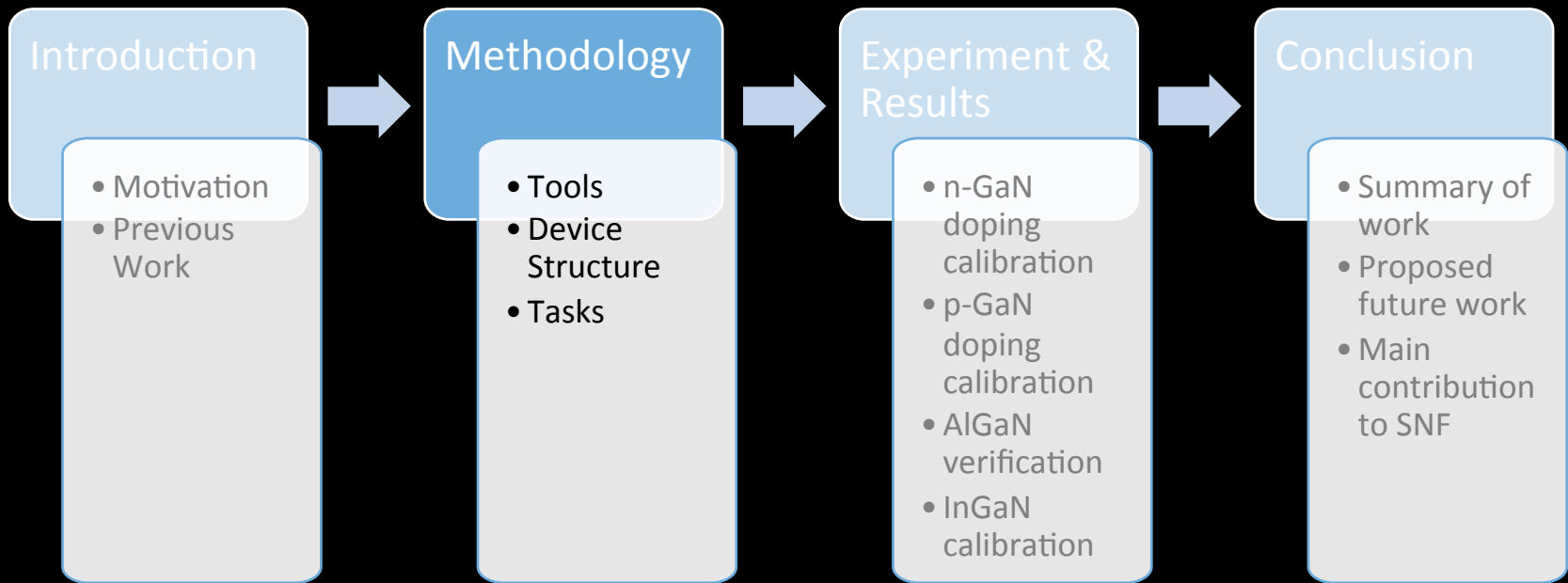
AlGaN

- Verify growth thickness for $\text{Al}_{0.2}\text{Ga}_{0.8}\text{N}$

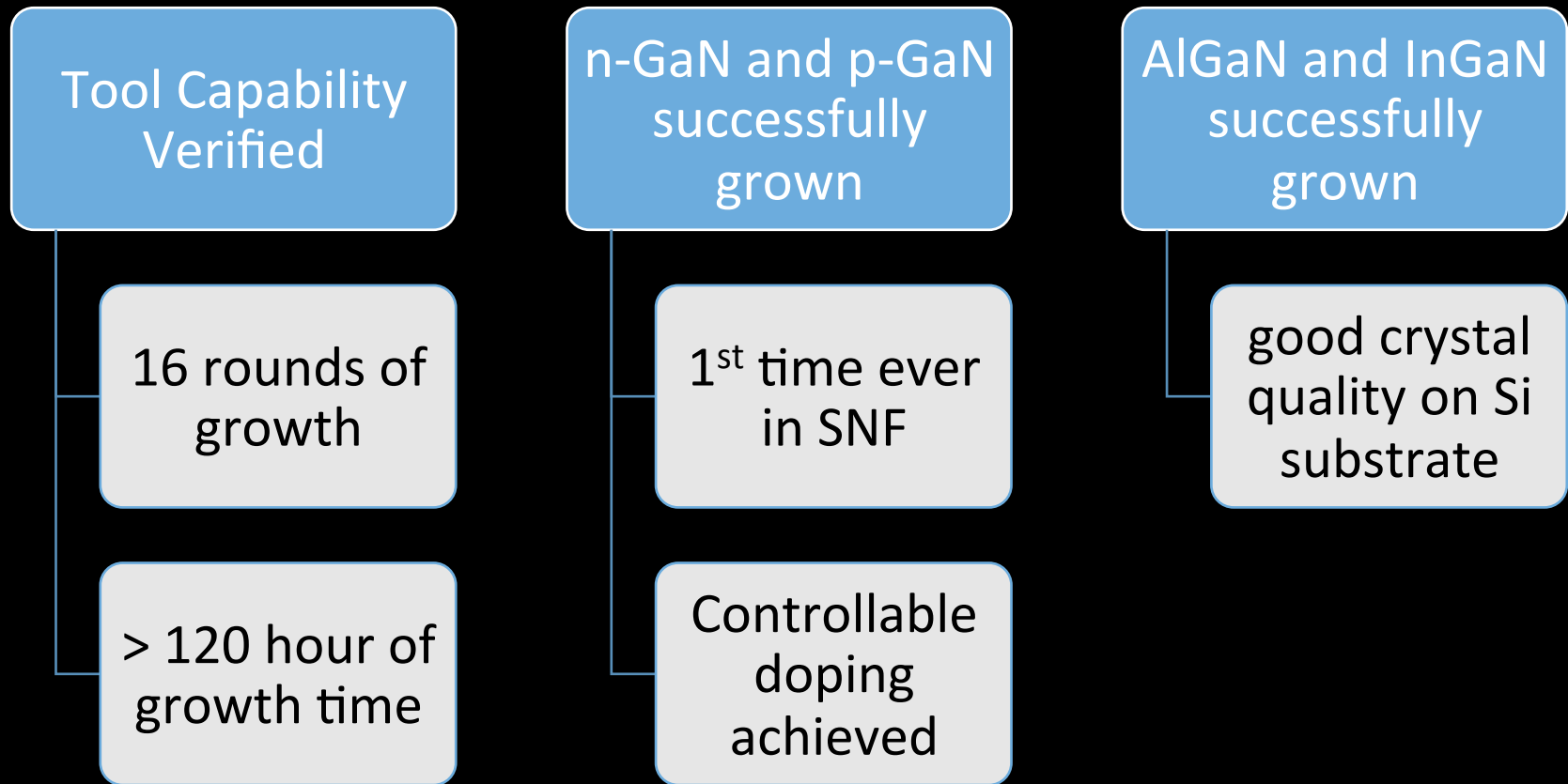
InGaN

- Investigate relation between indium composition and growth temperature
- Verify crystal quality

Outline

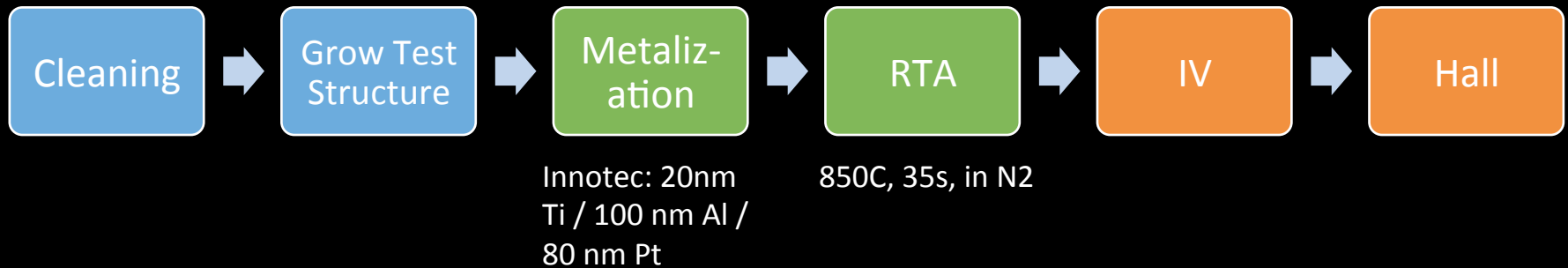
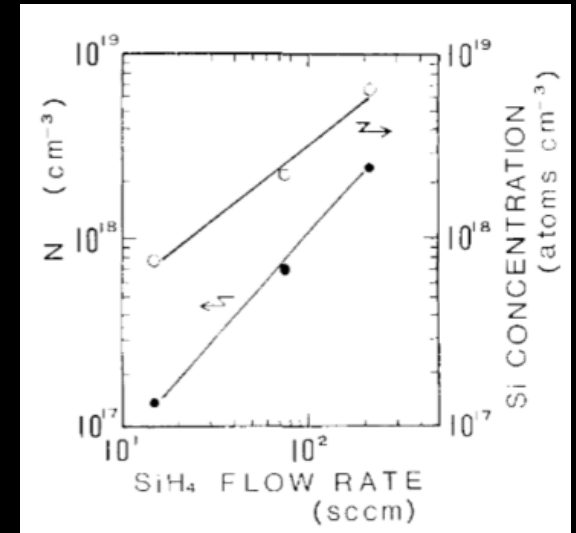


Experiment & Results - Summary

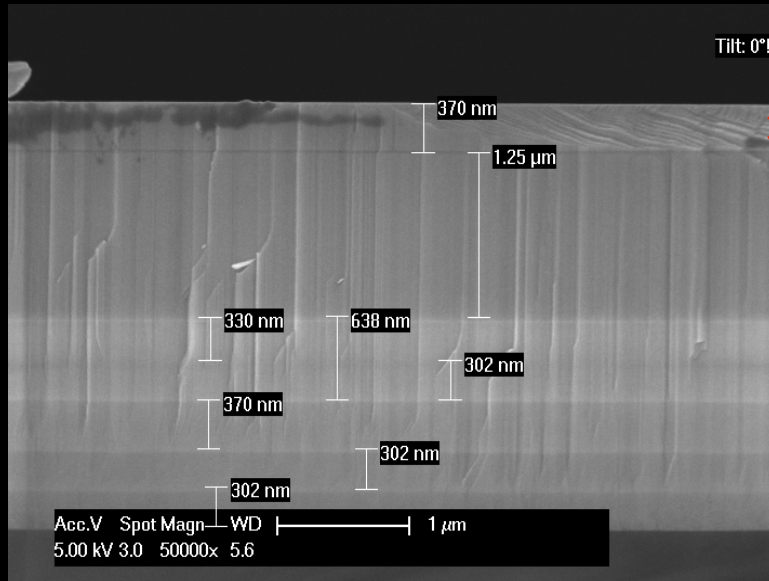


n-GaN Doping Calibration

- Doping with SiH_4 diluted with H_2
- n-doping depends mainly on the ratio of Si and Ga flow rates
 - Vary SiH_4 flow, measure mobility, resistivity and doping density



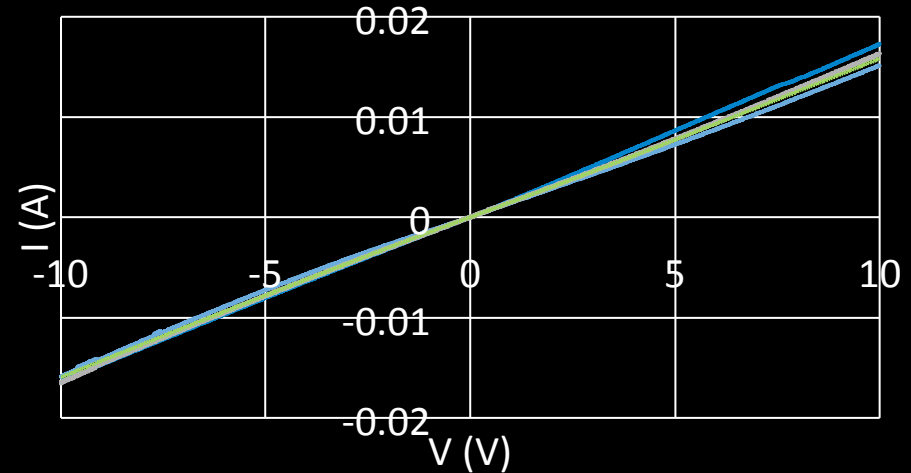
n-GaN Doping Calibration Results – SEM & IV



Smooth growth interface and expected thickness achieved

IV measurement indicates good conductivity

- Good contact quality
- RTA does not have significant effects



- Pair 1, w/o RTA - - - Pair 1, w/ RTA
- Pair 2, w/o RTA - - - Pair 2, w/ RTA

n-GaN Doping Calibration Results – Hall Measurement

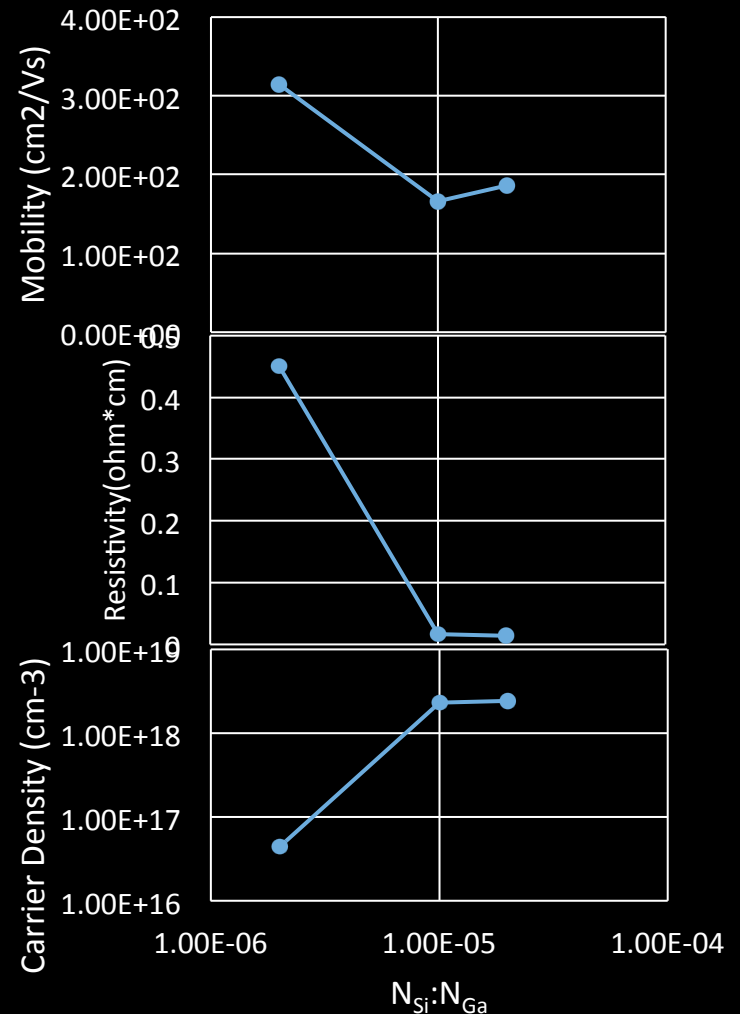
$N_{Si}:N_{Ga}$	Mobility (cm ² /Vs)	Resistivity (ohm*cm)	Carrier Density (cm ⁻³)
2.00E-06	3.2E22	0.45	4.4E16
1.00E-05	1.7E2	0.017	2.3E18
2.00E-05	1.9E2	0.014	2.4E18

Growth Temp	Growth Time	Growth Pressure	SEM Thickness
1295C	680 sec	200 mbar	352 nm

Carrier density of $\sim 1E18$ cm⁻³ achieved.

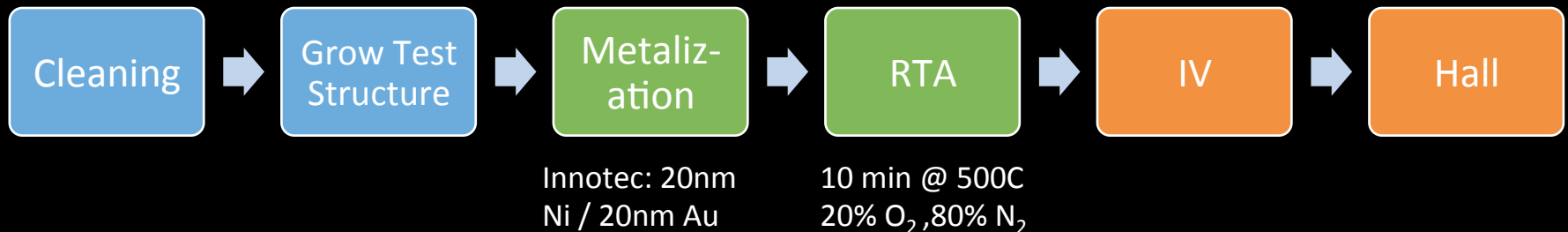
❖ Most optoelectronic application requires 1E17~1E18 cm⁻³

Mobility measurement result indicates good material quality.



p-GaN Doping Calibration

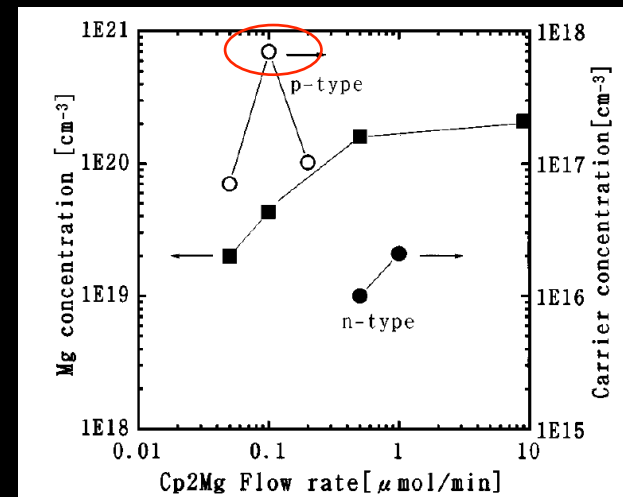
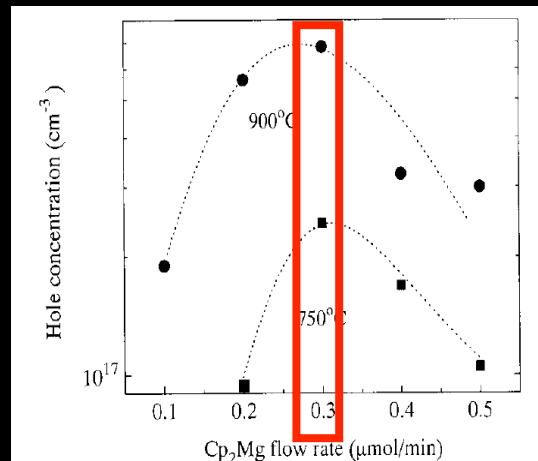
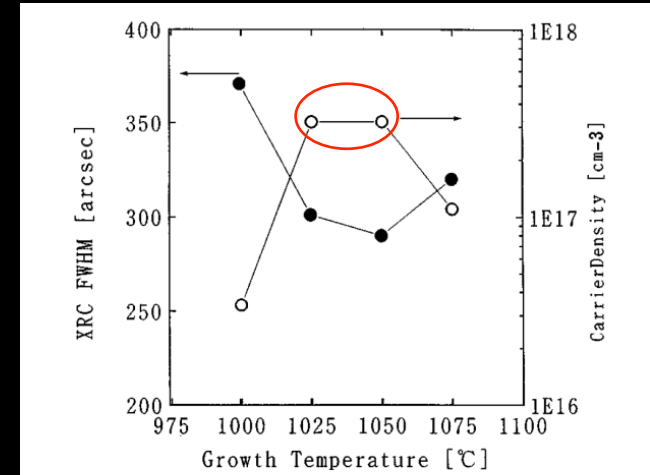
- Doping with Cp_2Mg (Bis(cyclopentadienyl)magnesium).
- Calibration very complicated: p-doping depends on multiple parameters:
 - Mg and Ga flow rate ratio
 - Growth temperature
 - Post growth annealing (Mg dopant activation) temperature & time
 - p-GaN metal contact is also difficult to make



Experiment Design – Parameter & Variables

- Mg and Ga flow rate ratio
- Growth temperature
- Post growth annealing (Mg dopant activation) temperature & time
- p-GaN metal contact is also difficult to make

Extremely narrow growth window!!



Tokunaga, H., et al. "Growth condition dependence of Mg-doped GaN film grown by horizontal atmospheric MOCVD system with three layered laminar flow gas injection." *Journal of crystal growth* 189 (1998):

p-GaN Doping Calibration Results

- Parameter Matrix

Annealing Temp. = 750 C

		N_{Mg}/N_{Ga}			
Growth Temp. (C)		0.0017	0.0034	0.0068	0.0092
Growth Temp. (C)	1200				
	1230				
	1295				

Annealing Temp. = 990 C

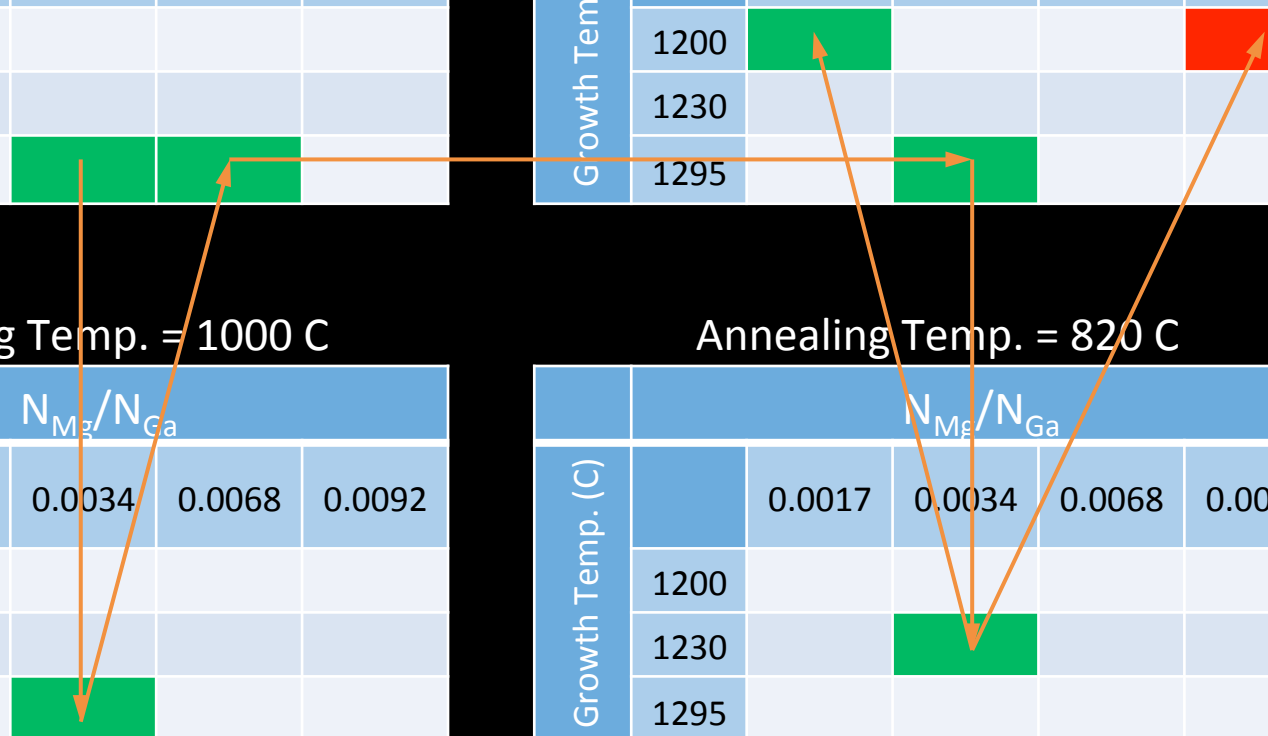
		N_{Mg}/N_{Ga}			
Growth Temp. (C)		0.0017	0.0034	0.0068	0.0092
Growth Temp. (C)	1200				
	1230				
	1295				

Annealing Temp. = 1000 C

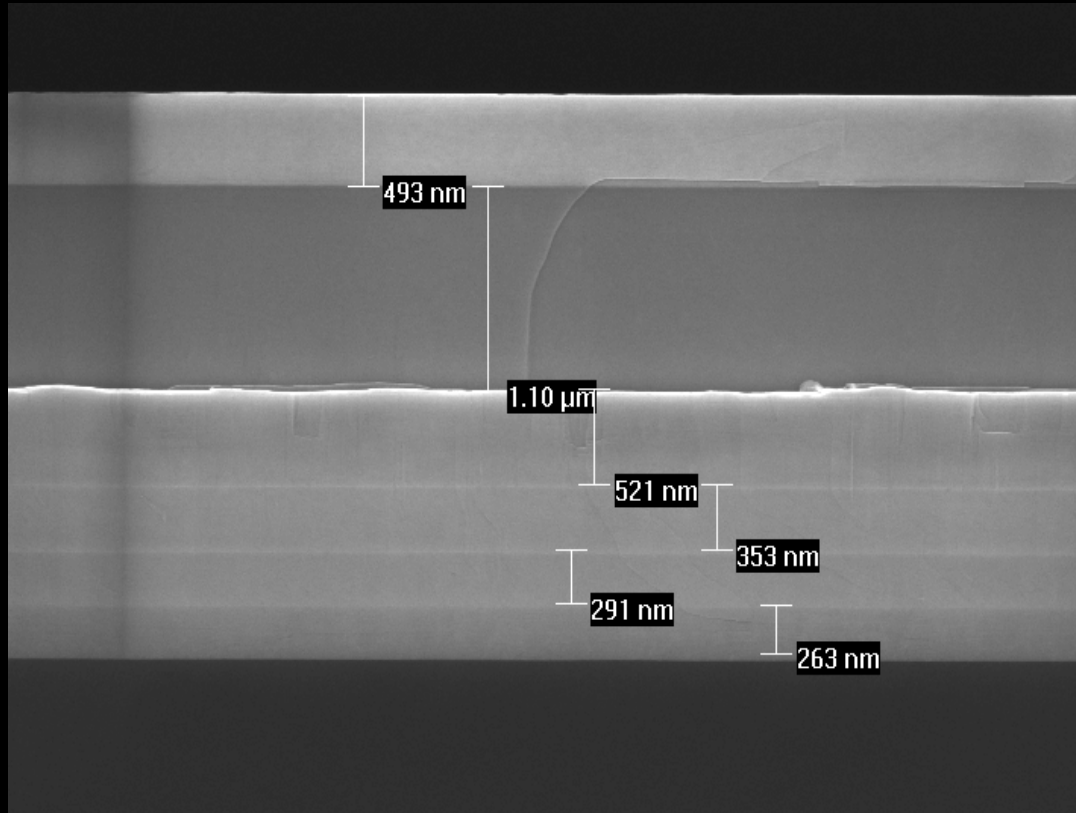
		N_{Mg}/N_{Ga}			
Growth Temp. (C)		0.0017	0.0034	0.0068	0.0092
Growth Temp. (C)	1200				
	1230				
	1295				

Annealing Temp. = 820 C

		N_{Mg}/N_{Ga}			
Growth Temp. (C)		0.0017	0.0034	0.0068	0.0092
Growth Temp. (C)	1200				
	1230				
	1295				



p-GaN Doping Calibration Results - SEM



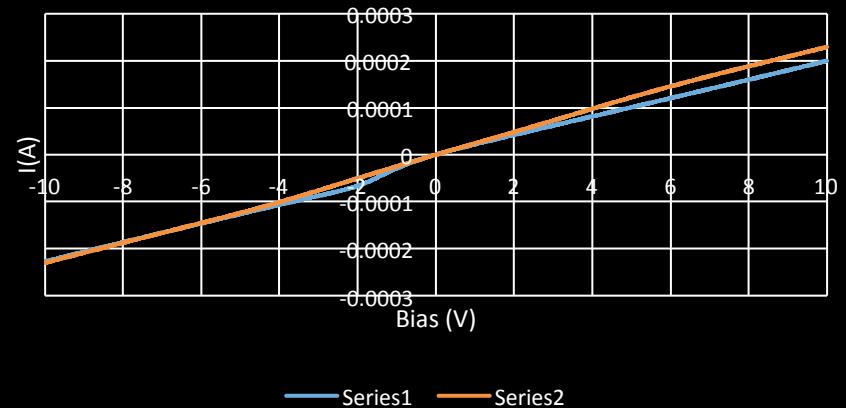
Smooth growth interface. Expected thickness achieved

p-GaN Doping Calibration Results - IV

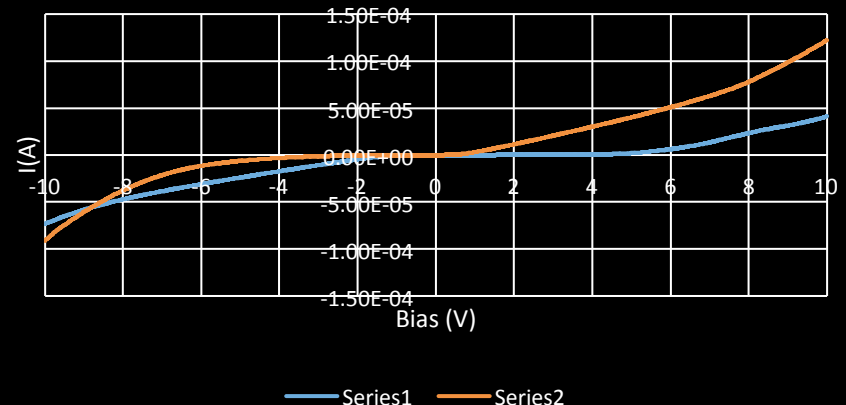
The contact will be ohmic only if the carrier density is sufficiently high

- ❖ Carrier density measurement relies on good contact
- Very challenging to conduct Hall measurement
- Contact annealing is crucial

Good Contact



Bad Contact



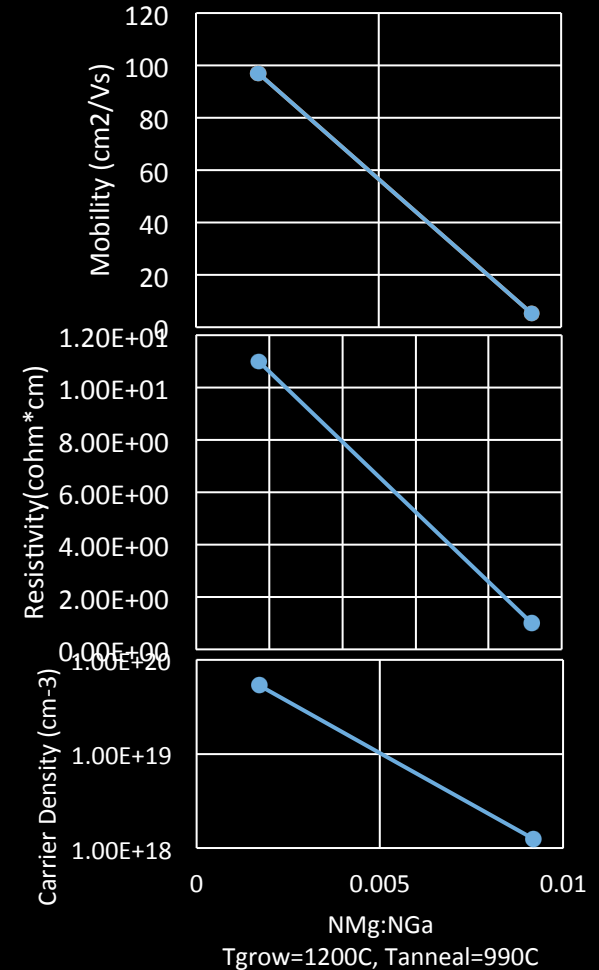
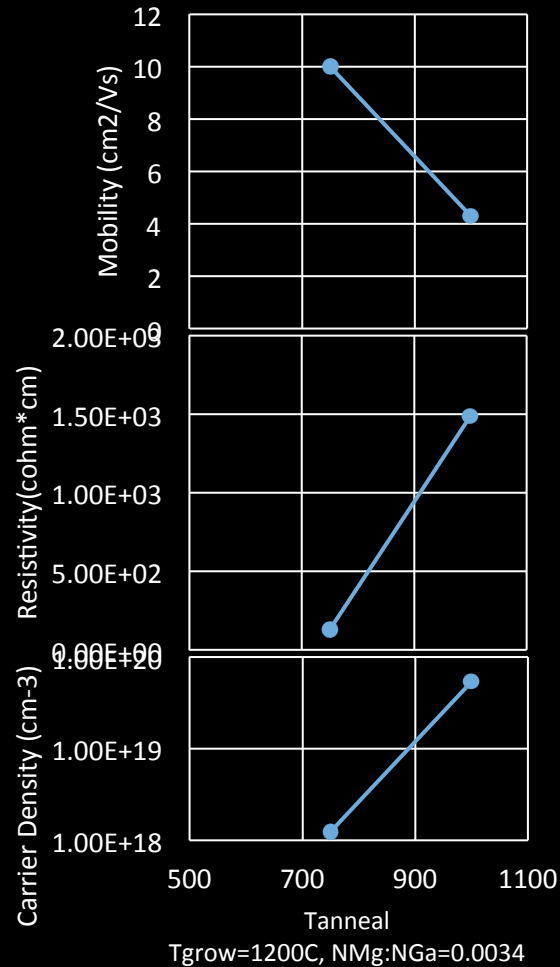
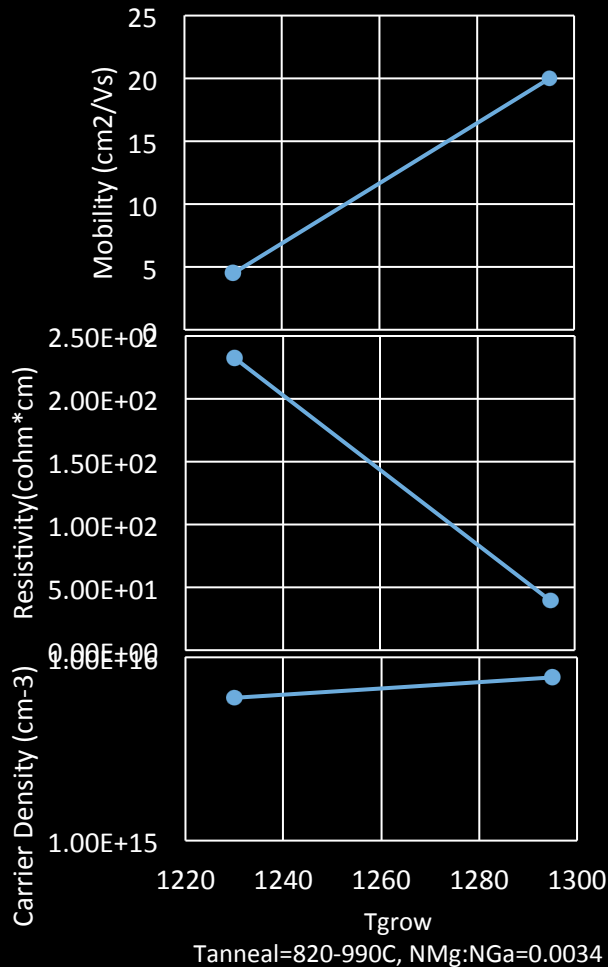
p-GaN Doping Calibration Results

– Hall Measurement

$N_{\text{Mg}}/N_{\text{Ga}}$	Growth Temp. (C)	Annealing Temp. (C)	Thickness (nm)	Mobility (cm ² /Vs)	Resistivity (ohm*cm)	Doping Density (cm ⁻³)
0.0034	1295	750	425	10	1.28E+02	9.41E+14
0.0034	1295	1000	350	4.3	1.49E+03	1.01E+16
0.0068	1295	750	336	7.6	1.68E+03	4.76E+14
0.0034	1295	990	450	20	3.94E+01	7.73E+15
0.0034	1230	820	500	4.5	2.33E+02	6.00E+15
0.00918	1200	990	200	5.3	1.00E+00	1.25E+18
0.0017	1200	990	500	97	1.10E+01	5.34E+19

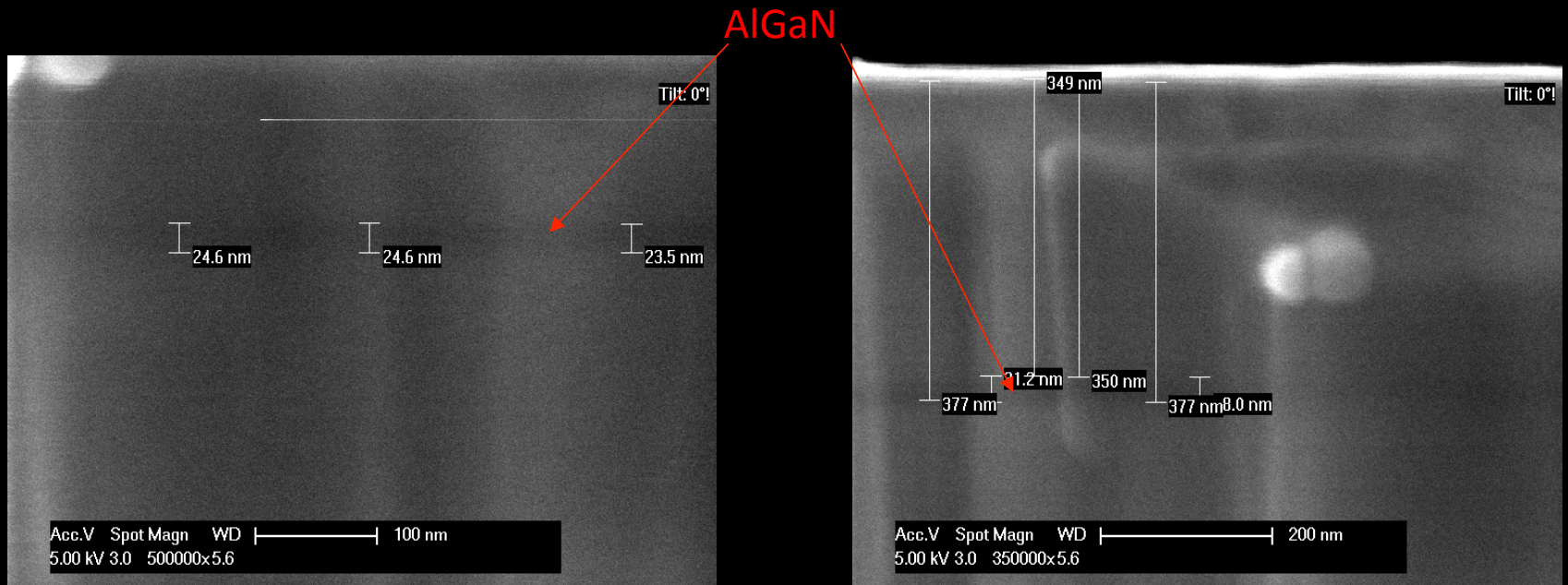
Red data are reasonable estimations.

p-GaN Doping Calibration Results – Hall Measurement



AlGaN Growth Verification

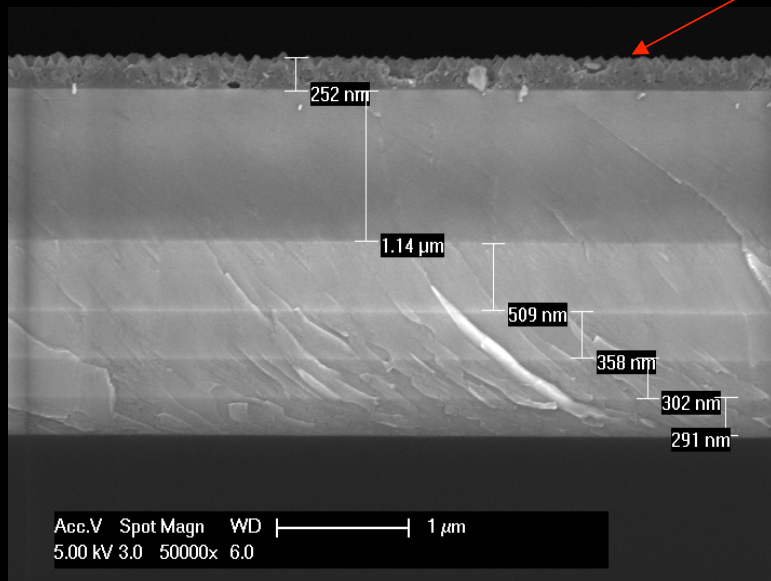
$N_{Al}:N_{Ga}$	NH3 Flow	Growth Temp	Growth Time	Growth Pressure	Thickness
0.1043	6.70E+02	1295 C	180 sec	100 mbar	23 nm



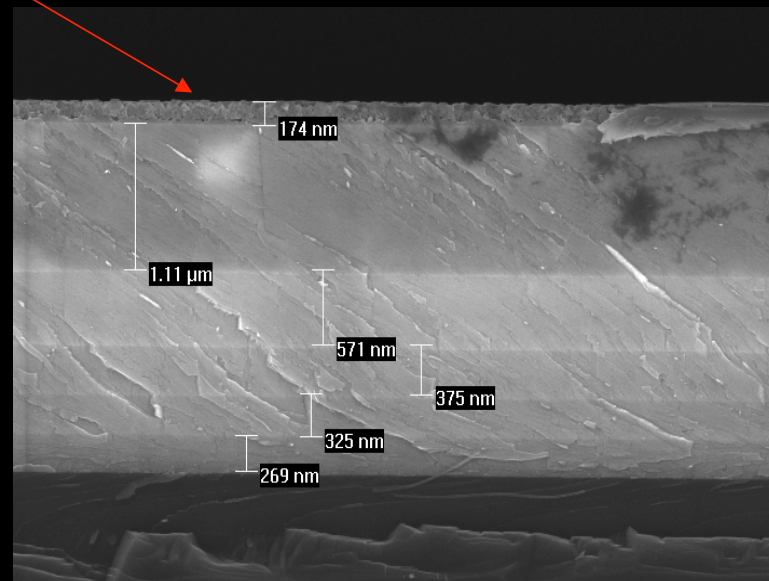
InGaN Growth Verification

$N_{Al}:N_{Ga}$	NH3 Flow	Growth Temp	Growth Time	Growth Pressure	Thickness	In %
1.42	4000	790C	2700 sec	400 mbar	250 nm	45
1.42	4000	850C	2700 sec	400 mbar	170 nm	36

InGaN



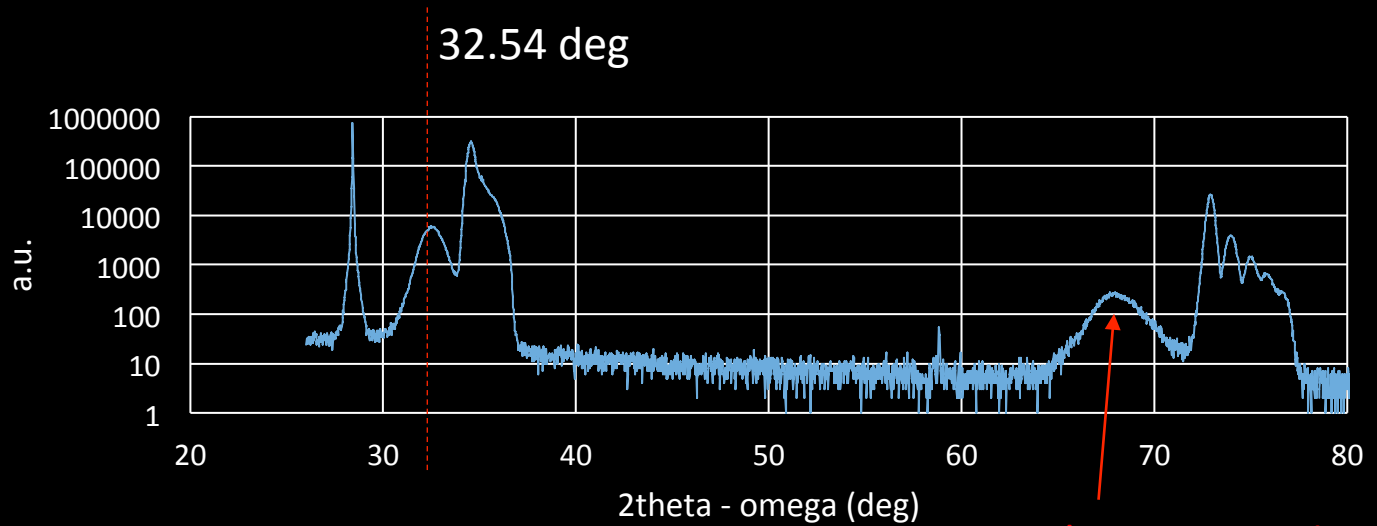
790 C



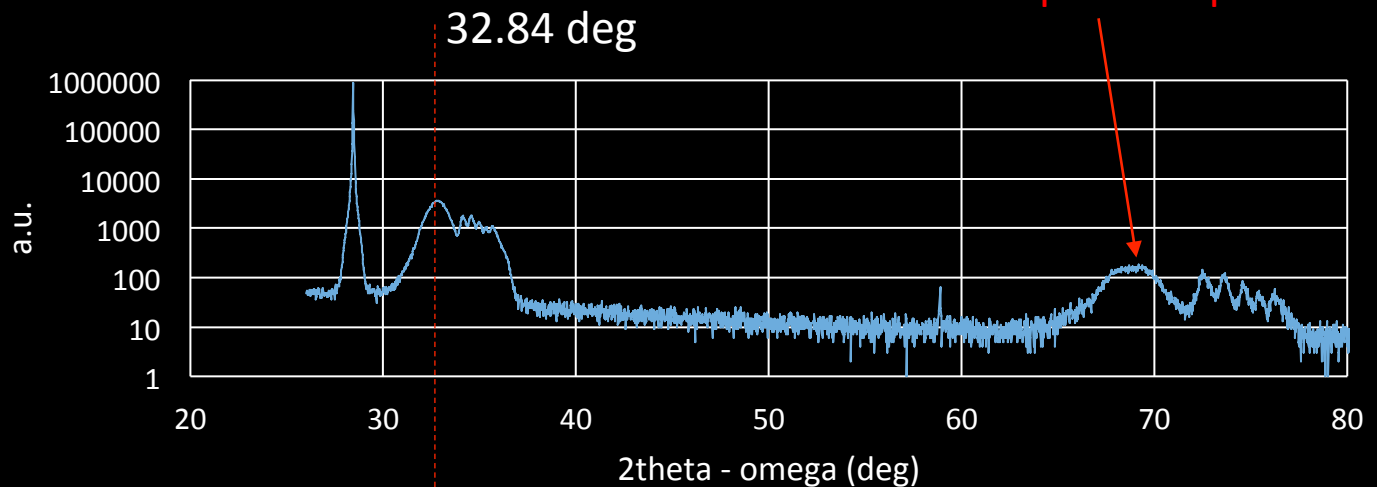
850 C

InGaN Growth Verification - XRD

790 C
In % = 45 %



850 C
In % = 36 %

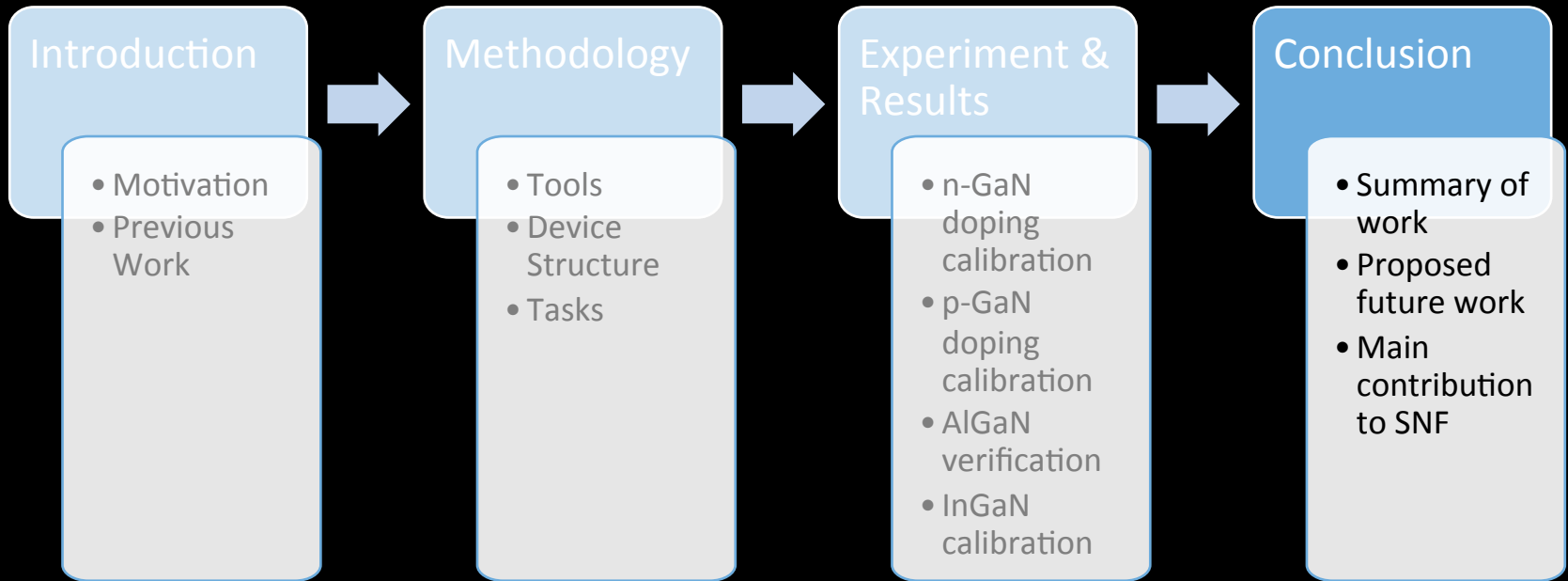


Other work

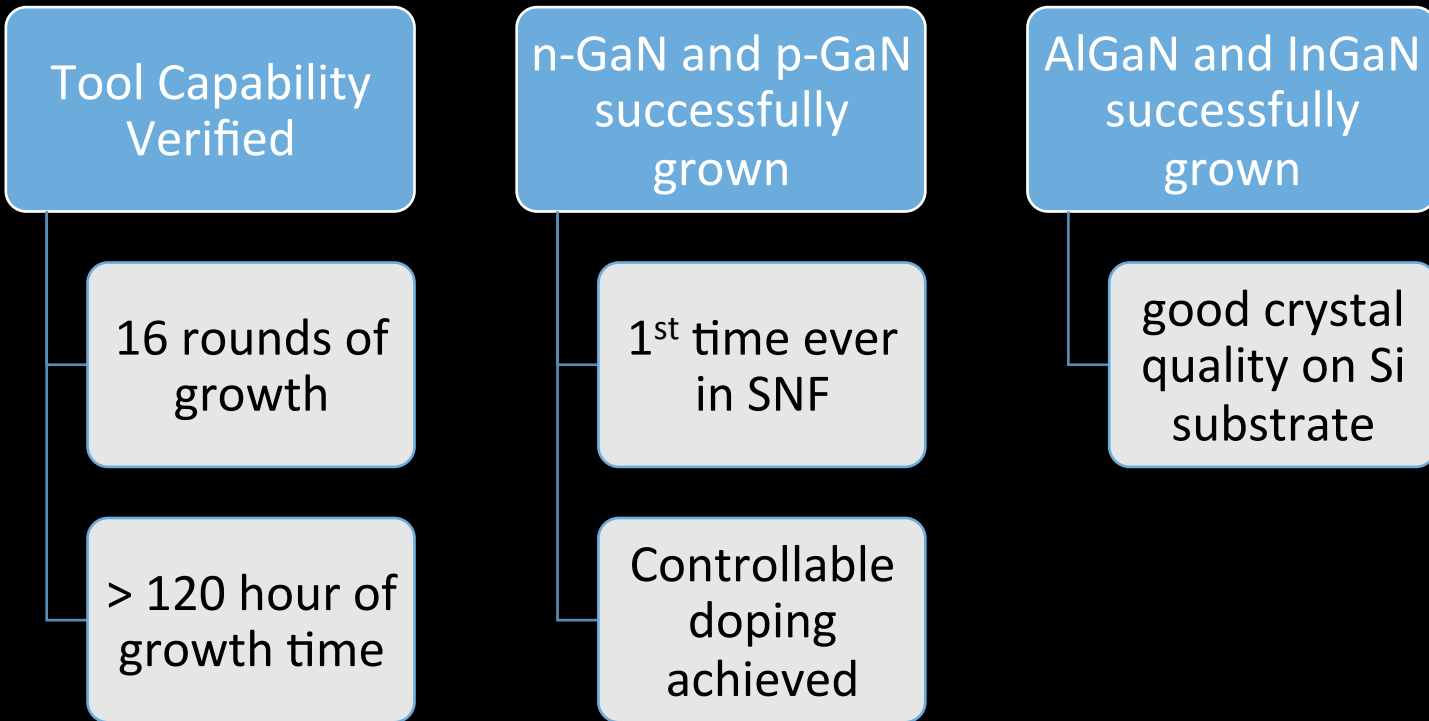
- p-GaN growing thickness investigated
- RTA process for p-GaN investigated
- Growth chamber baking & brushing requirement investigated
- Indium contact and Ti/Al/Au contact for n-GaN compared

Details will be included in the final report

Outline



Summary



Proposed Future Work

- Calibrate lower doping of p-GaN
- More InGaN and AlGaN calibration
- Try LED growth and fabrication

Main Contribution to SNF

n-GaN, p-GaN, AlGaN and InGaN growths are verified and calibrated

- Multiple new materials available at SNF!

Subsequent process investigated

- Metal contact recipe
- Metal annealing recipe

MOCVD capability tested, insights gained on MOCVD operation

- Valuable information for future Aix-ccs users

Acknowledgement

- Thanks to Xiaoqing for the mentorship, training on the MOCVD system and other help on the project
- Thanks to Prof. Howe, Dr. Mary Tang and other EE412 mentors for their valuable advice.
- Thanks to Prof. Harris for providing funding for SEM and other characterization tools.